HALOGEN

FREE



### Vishay Semiconductors

# Hyperfast Rectifier, 8 A FRED Pt®



PRIMARY CHARACTERISTICS								
I <sub>F(AV)</sub>	8 A							
V <sub>R</sub>	600 V							
V <sub>F</sub> at I <sub>F</sub>	1.3 V							
t <sub>rr</sub> (typ.)	16 ns							
T <sub>J</sub> max.	175 °C							
Package TO-220AC 2L								
Circuit configuration	Single							

#### **FEATURES**

- Hyperfast soft recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- True 2 pin package
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912">www.vishav.com/doc?99912</a>

### **DESCRIPTION / APPLICATIONS**

Hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		600	V
Average rectified forward current in DC	I <sub>F(AV)</sub>	T <sub>C</sub> = 146 °C	8	
Non-repetitive peak surge current	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C	80	Α
Repetitive peak surge current Square wave 20 kHz duty cycle (50 %)	I <sub>FRM</sub>	T <sub>C</sub> = 137 °C	16	
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-65 to +175	°C

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	I <sub>R</sub> = 100 μA	600	-	-	.,				
Forward voltage		I <sub>F</sub> = 8 A	-	2.0	2.65	V				
Forward voitage	V <sub>F</sub>	I <sub>F</sub> = 8 A, T <sub>J</sub> = 150 °C	-	1.3	1.85					
Reverse leakage current	I <sub>R</sub>	$V_R = V_R$ rated	-	0.02	12					
neverse leakage current		$T_J = 150 ^{\circ}\text{C},  V_R = V_R  \text{rated}$	-	15	100	μΑ				
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 600 V	-	6	-	pF				
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	8	-	nH				



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<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1 \text{ A}, dI_F/dt = 100$	$I_F = 1 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$			23			
Dovorce receivery time		$I_F = 8 \text{ A}, dI_F/dt = 100$	$I_F = 8 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$			28	no		
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	21	-	ns		
		T <sub>J</sub> = 125 °C		-	39	-			
		T <sub>J</sub> = 25 °C	$I_F = 8 \text{ A},$	-	3	-	- A		
Peak recovery current	IRRM	T <sub>J</sub> = 125 °C	dl <sub>F</sub> /dt = 200 A/μs, V <sub>B</sub> = 390 V	-	5	-			
Deviana vacavani ahavaa	0	T <sub>J</sub> = 25 °C		-	36	-			
Reverse recovery charge	$Q_{rr}$	T <sub>J</sub> = 125 °C		-	108	-	nC		
Reverse recovery time	t <sub>rr</sub>		I <sub>F</sub> = 8 A,	-	30	-	ns		
Peak recovery current	I <sub>RRM</sub>	T <sub>J</sub> = 125 °C	$T_J = 125  ^{\circ}\text{C}$ $dI_F/dt = 600  \text{A/}\mu\text{s},$	-	13	-	Α		
Reverse recovery charge	Q <sub>rr</sub>		$V_{R} = 390 \text{ V}$	-	205	-	nC		

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65	-	175	°C				
Thermal resistance, junction-to-case	R <sub>thJC</sub>		-	2.0	2.6					
Thermal resistance, junction-to-ambient	R <sub>thJA</sub>	Typical socket mount	-	-	70	°C/W				
Typical thermal resistance, case-to-heatsink	R <sub>thCS</sub>	Mounting surface, flat, smooth and greased	-	0.5	-					
Maiabt			-	2	-	g				
Weight			-	0.07	-	oz.				
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)				
Marking device Case style TO-220AC 2L ETH0806				0806						



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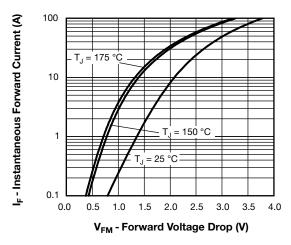


Fig. 1 - Typical Forward Voltage Drop Characteristics

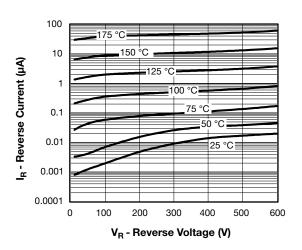


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

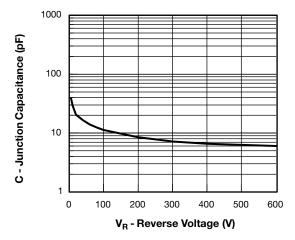


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

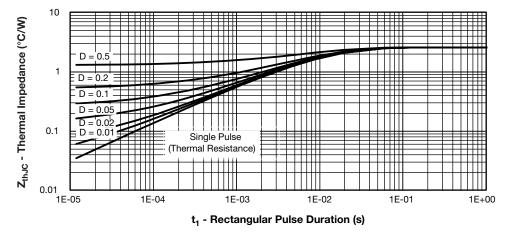


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

F - Average Power Loss (W)

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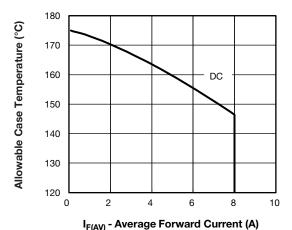


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

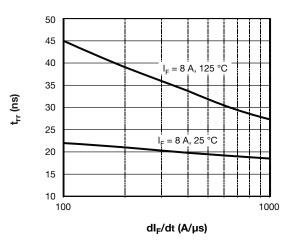


Fig. 7 - Typical Reverse Recovery vs. dI<sub>F</sub>/dt

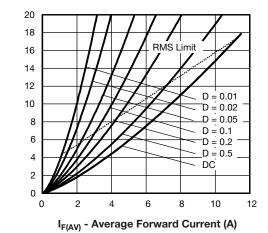


Fig. 6 - Forward Power Loss Characteristics

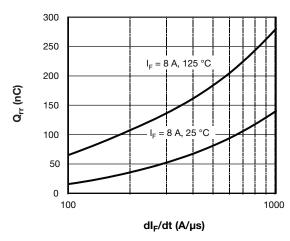
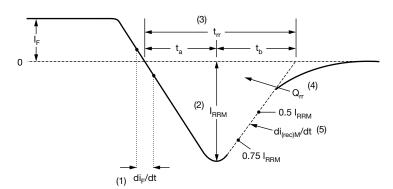


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2) I<sub>RRM</sub> peak reverse recovery current
- (3)  $t_{rr}$  reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through 0.75  $I_{RBM}$  and 0.50  $I_{RBM}$  extrapolated to zero current.
- (4)  $\mathbf{Q}_{\rm rr}$  area under curve defined by  $\mathbf{t}_{\rm rr}$  and  $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} x I_{RRM}}{2}$$

(5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$ 

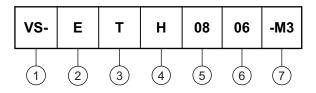
Fig. 9 - Reverse Recovery Waveform and Definitions



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### **ORDERING INFORMATION TABLE**

### Device code



1 - Vishay Semiconductors product

2 - Circuit configuration:

E = single

**3** - T = 2L TO-220AC

4 - H = hyperfast recovery time

5 - Current code: 08 = 8 A

6 - Voltage code: 06 = 600 V

7 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)									
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION							
VS-ETH0806-M3	50	Antistatic plastic tubes							

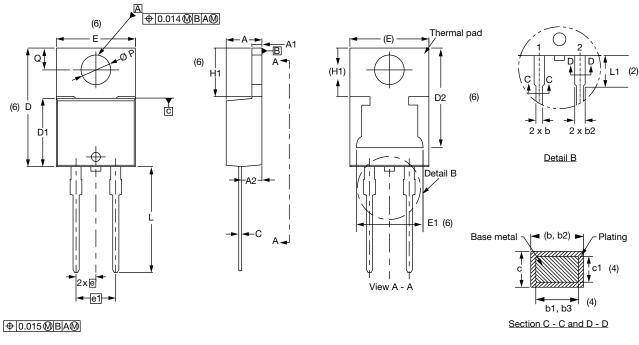
LINKS TO RELATED DOCUMENTS								
Dimensions <u>www.vishay.com/doc?96156</u>								
Part marking information	www.vishay.com/doc?95391							



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### **TO-220AC 2L**

### **DIMENSIONS** in millimeters and inches



Lead tip

Conforms to JEDEC® outline TO-220AC

SYMBOL	MILLIN	IETERS	TERS INCHES NOTES	SYMBOL	MILLIM	IETERS	INC	HES	NOTES		
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES	STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.25	4.65	0.167	0.183		D2	11.68	13.30	0.460	0.524	6, 7
A1	1.14	1.40	0.045	0.055		E	10.11	10.51	0.398	0.414	3, 6
A2	2.50	2.92	0.098	0.115		E1	6.86	8.89	0.270	0.350	6
b	0.69	1.01	0.027	0.040		е	2.41	2.67	0.095	0.105	
b1	0.38	0.97	0.015	0.038	4	e1	4.88	5.28	0.192	0.208	
b2	1.20	1.73	0.047	0.068		H1	6.09	6.48	0.240	0.255	6
b3	1.14	1.73	0.045	0.068	4	L	13.52	14.02	0.532	0.552	
С	0.36	0.61	0.014	0.024		L1	3.32	3.82	0.131	0.150	2
c1	0.36	0.56	0.014	0.022	4	ØΡ	3.54	3.91	0.139	0.154	
D	14.85	15.35	0.585	0.604	3	Q	2.60	3.00	0.102	0.118	
D1	8.38	9.02	0.330	0.355						•	

#### Notes

- $^{(1)}$  Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3, and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- (7) Outline conforms to JEDEC® TO-220, except D2



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